

**Amendments to the Claims**

1. (currently amended) A sound-insulating floor covering component comprising:  
a rigid laminate or parquet panel including wood or timber-based materials, the panel having a bottom surface and a top appearance surface; and  
a layer of thermoplastic material firmly bonded to the bottom surface of the panel, wherein the layer of thermoplastic material is 0.1 to 5 mm thick.
2. (cancelled)
3. (currently amended) A sound-insulating floor covering component ~~according to claim 1~~ comprising:  
a rigid laminate or parquet panel including wood or timber-based materials, the panel having a bottom surface and a top appearance surface; and  
a layer of thermoplastic material firmly bonded to the bottom surface of the panel, in which the layer of thermoplastic material displays a marked physical relaxation behavior at ambient temperature.
4. (previously presented) A sound-insulating floor covering component according to claim 1, wherein the thermoplastic material is selected from the group consisting of polyvinyl formals, polyvinyl butyrals, polyvinyl ethers, polyisobutenes, copolymers including terpolymers of acrylonitrile, butadiene and styrene (ABS), copolymers of vinyl chloride and 2-ethylhexyl acrylate, copolymers of vinyl acetate and vinyl laurate, or blends of these polymers.
5. (previously presented) A sound-insulating floor covering component according to claim 1, wherein the thermoplastic material includes a filler.

6. (previously presented) A sound-insulating floor covering component according to claim 1, wherein thermoplastic material has an adhesive property for bonding to the bottom surface of the panel.

7. (previously presented) A sound-insulating floor covering component according to claim 1, wherein the panel is thicker than the layer of thermoplastic material.

8. (currently amended) A sound-insulating floor covering component ~~according to claim 1~~ comprising:  
a rigid laminate or parquet panel including wood or timber-based materials, the panel having a bottom surface and a top appearance surface; and  
a layer of thermoplastic material firmly bonded to the bottom surface of the panel, wherein the thermoplastic material, in a free-flowing state, was spread or rolled onto the bottom surface of the floor panel.

9. (currently amended) A sound-insulating floor covering component ~~according to claim 1~~ comprising:  
a rigid laminate or parquet panel including wood or timber-based materials, the panel having a bottom surface and a top appearance surface; and  
a layer of thermoplastic material firmly bonded to the bottom surface of the panel, wherein the thermoplastic material is heated and applied in a free-flowing state onto the bottom surface of the floor panel by spreading or roller application.

10. (currently amended) A sound-insulating floor covering component ~~according to claim 4~~ comprising:  
a rigid laminate or parquet panel including wood or timber-based materials, the panel having a bottom surface and a top appearance surface; and  
a layer of thermoplastic material firmly bonded to the bottom surface of the panel, wherein the thermoplastic material is selected from the group consisting of

polyvinyl formals, polyvinyl butyrals, polyvinyl ethers, polyisobutenes, copolymers including terpolymers of acrylonitrile, butadiene and styrene (ABS), copolymers of vinyl chloride and 2-ethylhexyl acrylate, copolymers of vinyl acetate and vinyl laurate, or blends of these polymers, and wherein the thermoplastic material includes a plasticiser.

11. (previously presented) A sound-insulating floor covering component according to claim 5, wherein the filler is a light organic substance.

12. (currently amended) A floor comprising a plurality of floor covering components according to claim 1 assembled over a floor substrate with the layer of thermoplastic material engaging the floor substrate.

13. (previously presented) A floor as set forth in claim 12, wherein the floor substrate includes a foam mat.

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**Amendments to the Drawings**

Enclosed is a drawing for filing in connection with this application.